Customer No.: 31561
Application No.: 10/063,737
Docket No.: 8727-US-PA

In The Claims:

Claim 1-15 (Cancelled)

Claim 16. (Previously Presented) A multi-layered substrate having a voltage reference signal circuit layout therein, comprising:

at least one signal layer having a plurality of signal traces;

a non-signaling layer having a voltage reference signal trace, wherein the voltage reference signal trace is wider than the other signal traces; and

a conductive plane between the signal layer and the non-signaling layer.

Claim 17. (Original) The multi-layered substrate of claim 16, wherein the non-signaling layer includes at least one power plane.

Claim 18. (Original) The multi-layered substrate of claim 16, wherein the non-signaling layer includes at least one ground layer plane.

Claim 19. (Original) The multi-layered substrate of claim 16, wherein the non-signaling layer includes at least one power plane and a plurality of signal traces.

Claim 20. (Original) The multi-layered substrate of claim 16, wherein the non-signaling layer includes at least one ground layer plane and a plurality of signal traces.

Claim 21. (Original) The multi-layered substrate of claim 16, wherein the conductive plane includes a ground plane.

Claim 22. (Original) The multi-layered substrate of claim 16, wherein the conductive plane includes a power plane.

Claim 23-26 (Cancelled)

Claim 27. (Newly Added) A multi-layered substrate, comprising:

a non-signaling layer having a voltage reference signal trace with a constant voltage input;

a signal layer having at least one signal trance; and

a conductive plane between the signal layer and the non-signaling layer.

Claim 28. (New) The multi-layered substrate of claim 27, wherein the non-signaling layer includes at least one power plane.

Claim 29. (New) The multi-layered substrate of claim 27, wherein the non-signaling layer includes at least one ground layer plane.

Claim 30. (New) The multi-layered substrate of claim 27, wherein the non-signaling layer includes at least one power plane and a plurality of signal traces.

Claim 31. (New) The multi-layered substrate of claim 27, wherein the non-signaling layer includes at least one ground layer plane and a plurality of signal traces.

Claim 32. (New) The multi-layered substrate of claim 27, wherein the conductive plane includes a ground plane.

Claim 33. (New) The multi-layered substrate of claim 27, wherein the conductive plane includes a power plane.